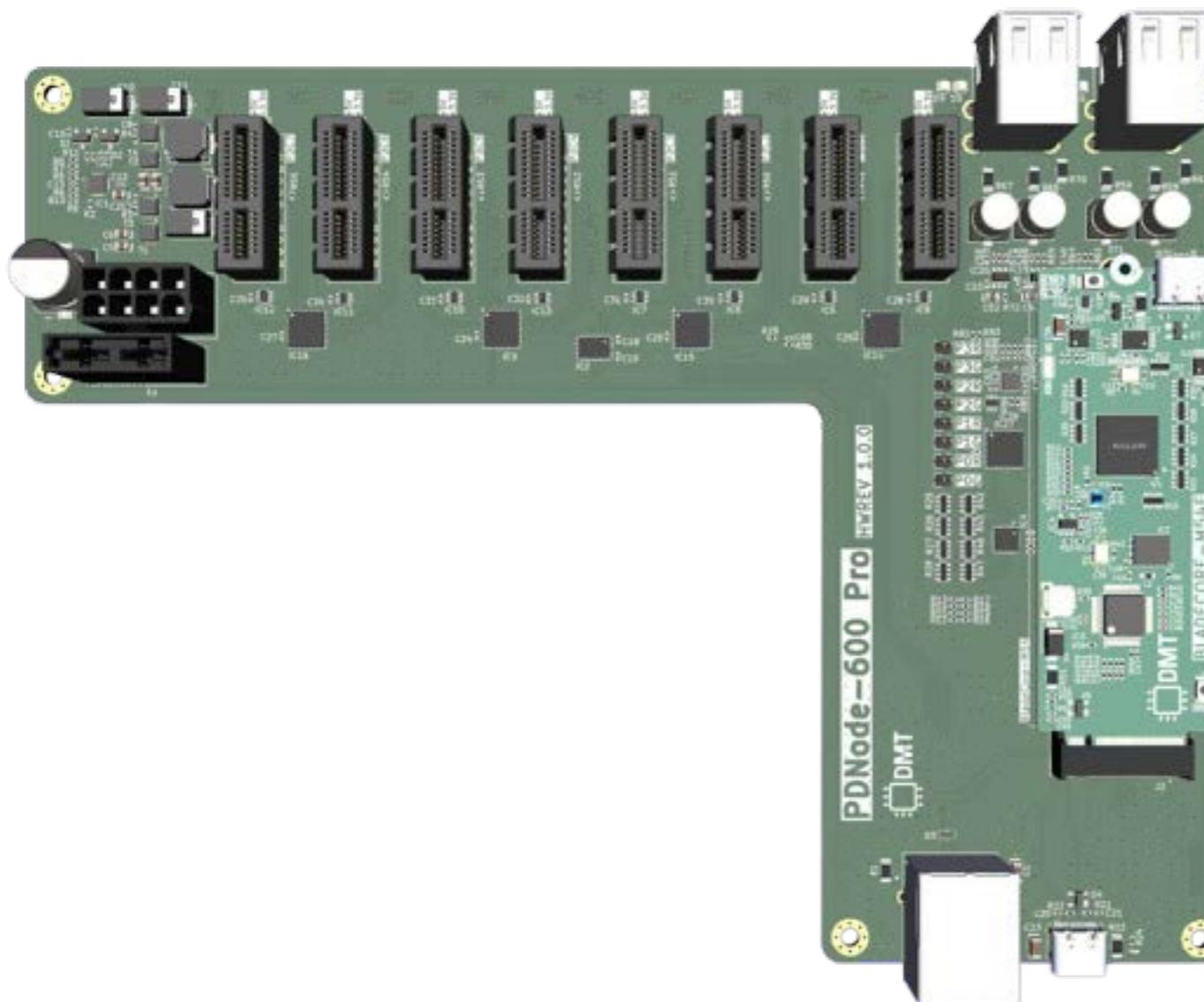
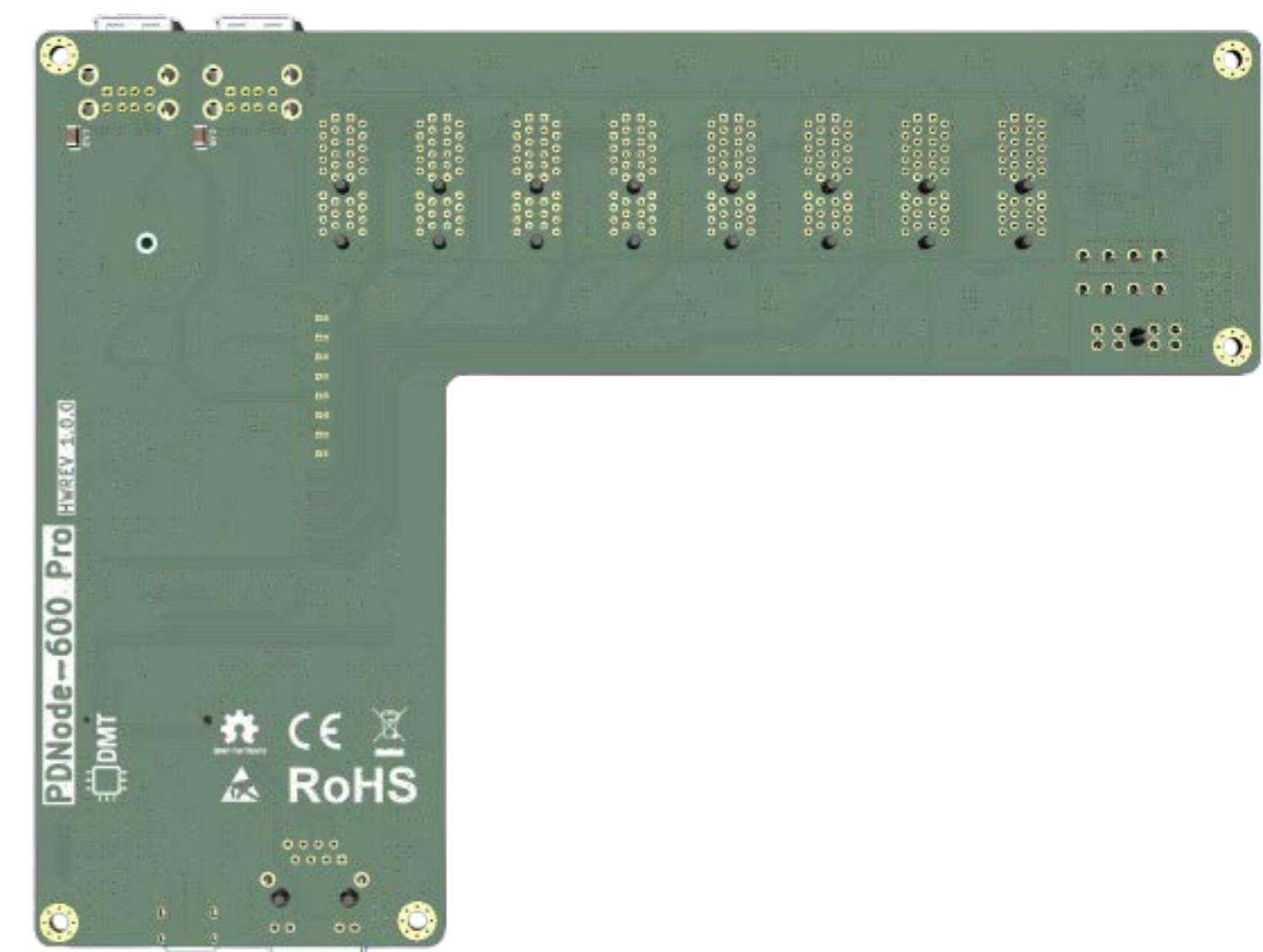


Baseboard Schematic Documentation**Top Preview****Bottom Preview**

|  DMT | Board Name: PDNode-600 | Project Name: Baseboard |
|---|--|---------------------------------------|
| Date: | File Name: PDNode_Baseboard.kicad_pcb | Revision: Variant: Pro |
| Sheet Title: | Company: | Designer: David Sipos Reviewer: |

Baseboard PCB Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

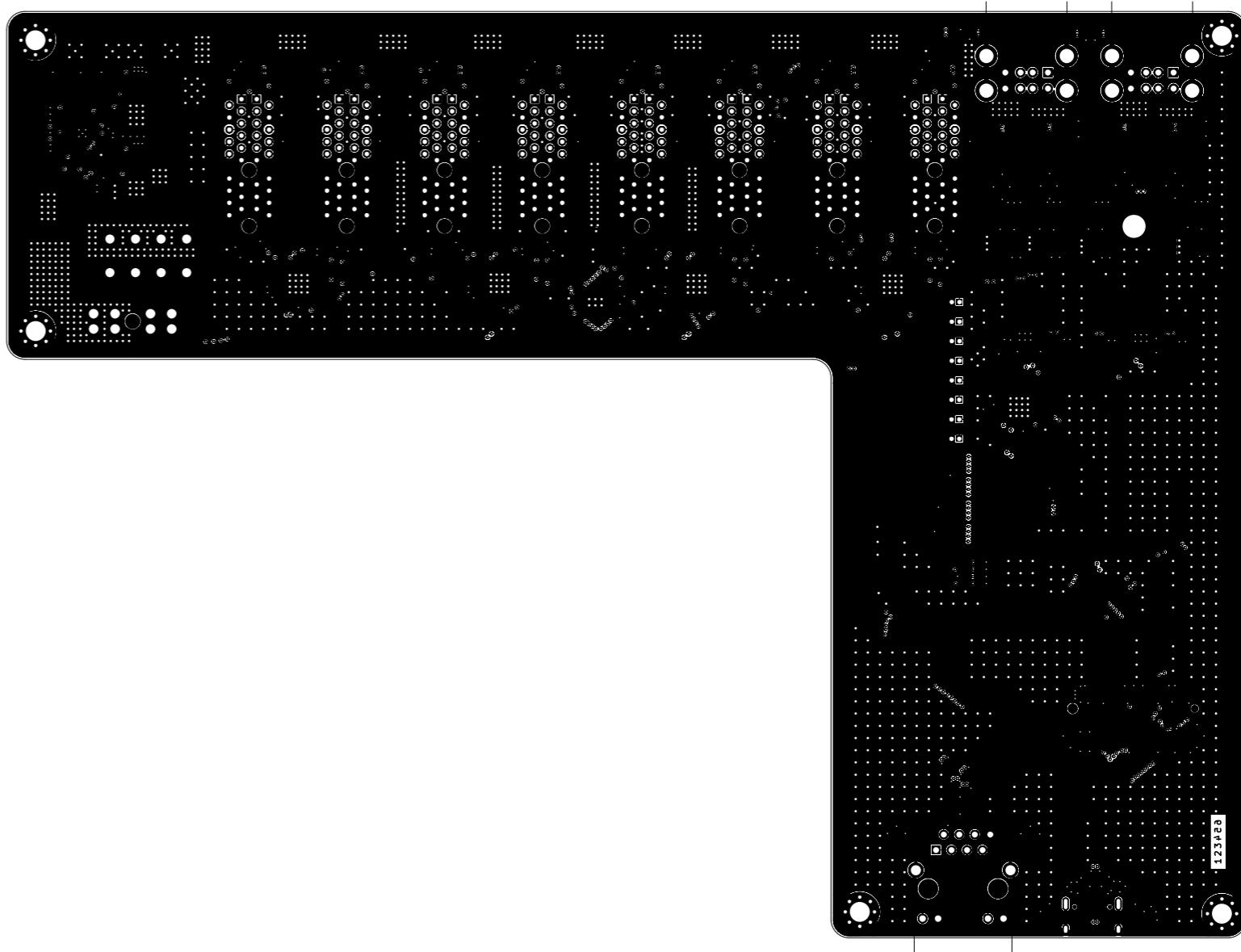
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- * 0.600mm / 0.0236" (0 holes + 4 slots)
- * 0.650mm / 0.0256" (16 holes)
- * 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- ◊ 1.499mm / 0.0590" (8 holes)
- ◊ 1.630mm / 0.0642" (2 holes)
- ⊗ 2.300mm / 0.0906" (8 holes)
- ⊗ 3.200mm / 0.1260" (5 holes)
- ⊗ 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)



Board Name:

PDNode-600

Project Name:

Baseboard

Date:

PDNode_Baseboard.kicad_pcb

Revision:

Pro

Sheet Title:

Company:

Designer:
David Sipos
Reviewer:

Size:

A3

Sheet:

1 of 1

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

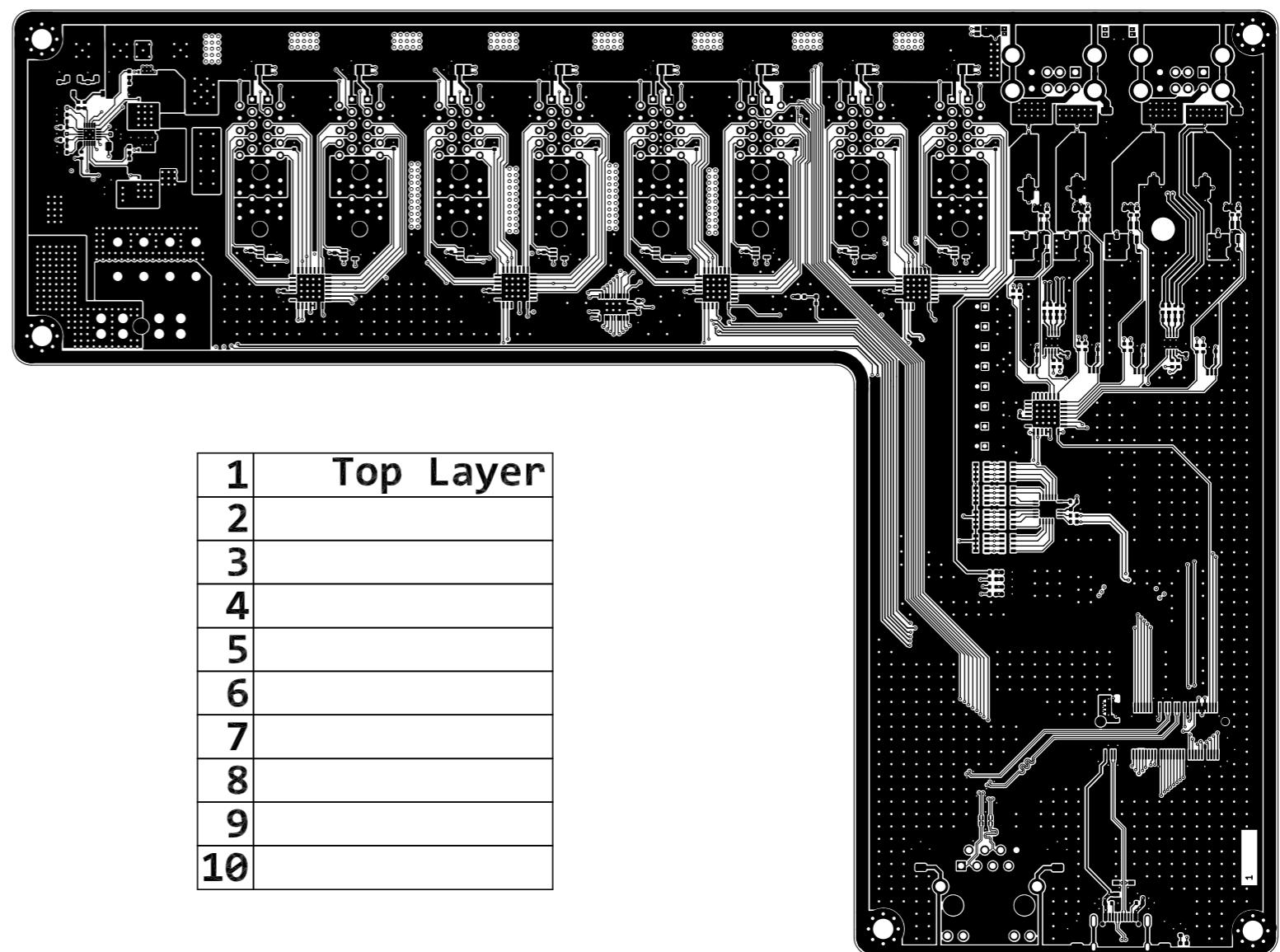
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



| 1 | Top Layer |
|----|-----------|
| 2 | |
| 3 | |
| 4 | |
| 5 | |
| 6 | |
| 7 | |
| 8 | |
| 9 | |
| 10 | |

PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- * 0.600mm / 0.0236" (0 holes + 4 slots)
- * 0.650mm / 0.0256" (16 holes)
- * 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- ❖ 1.400mm / 0.0551" (8 holes)
- ❖ 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- ❖ 2.300mm / 0.0906" (8 holes)
- ❖ 3.200mm / 0.1260" (5 holes)
- ❖ 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | | |
|-------|----------------------------|---------------|---------------------------------------|
| | Board Name: | Project Name: | |
| | PDNode-600 | Baseboard | |
| | File Name: | Revision: | |
| | PDNode_Baseboard.kicad_pcb | Variant: | |
| Date: | Sheet Title: | Company: | Designer: David Sipos Reviewer: |
| | | | Size: A3 |
| | | | Sheet: 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

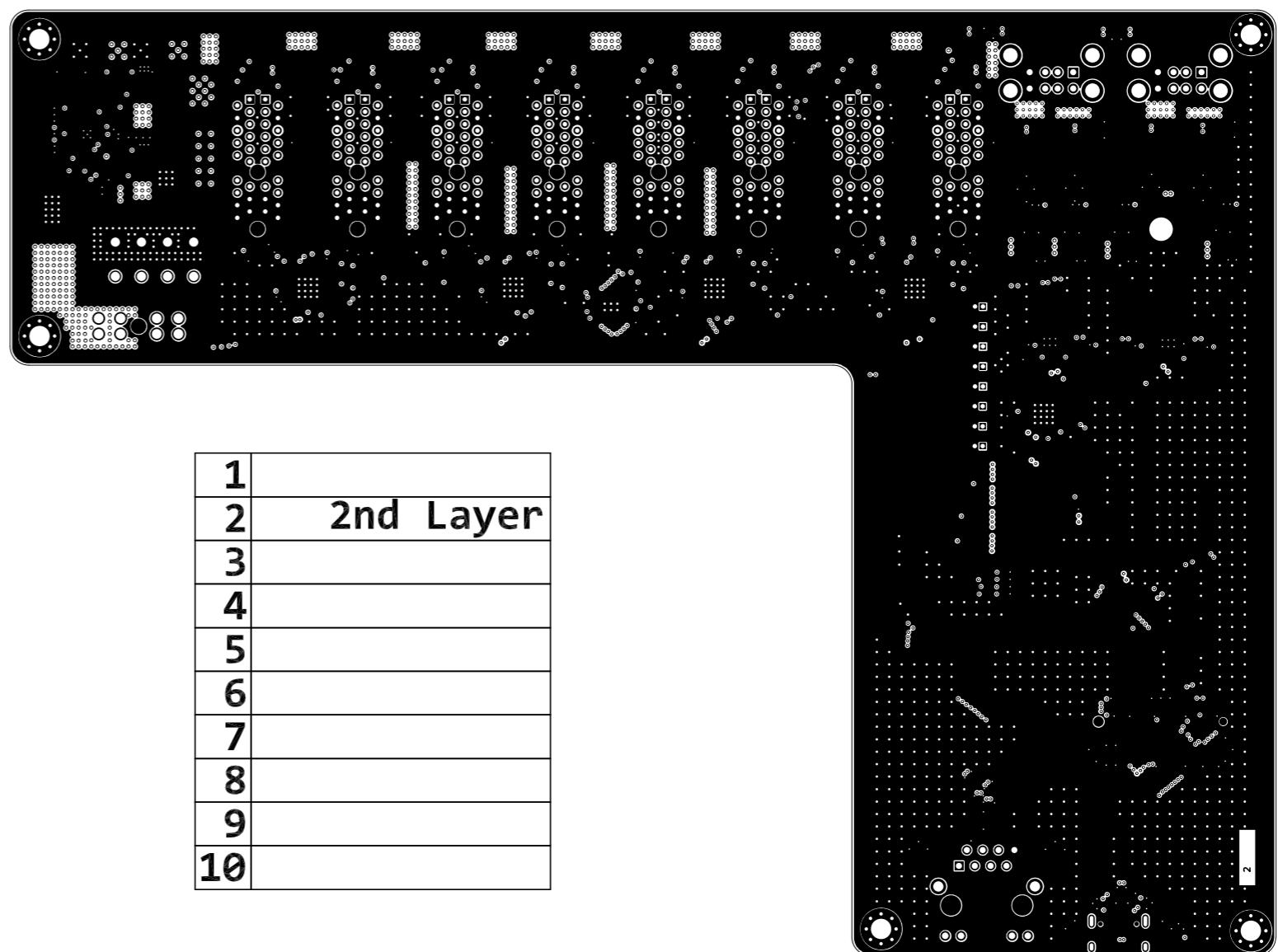
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



- | |
|----|
| 1 |
| 2 |
| 3 |
| 4 |
| 5 |
| 6 |
| 7 |
| 8 |
| 9 |
| 10 |

PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)



| | |
|--|--|
| Board Name: PDNode-600 | Project Name: Baseboard |
| Date: PDNode_Baseboard.kicad_pcb | Revision: Variant: Pro |
| Sheet Title: Company: Designer: Reviewer: | Size: Sheet: A3 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

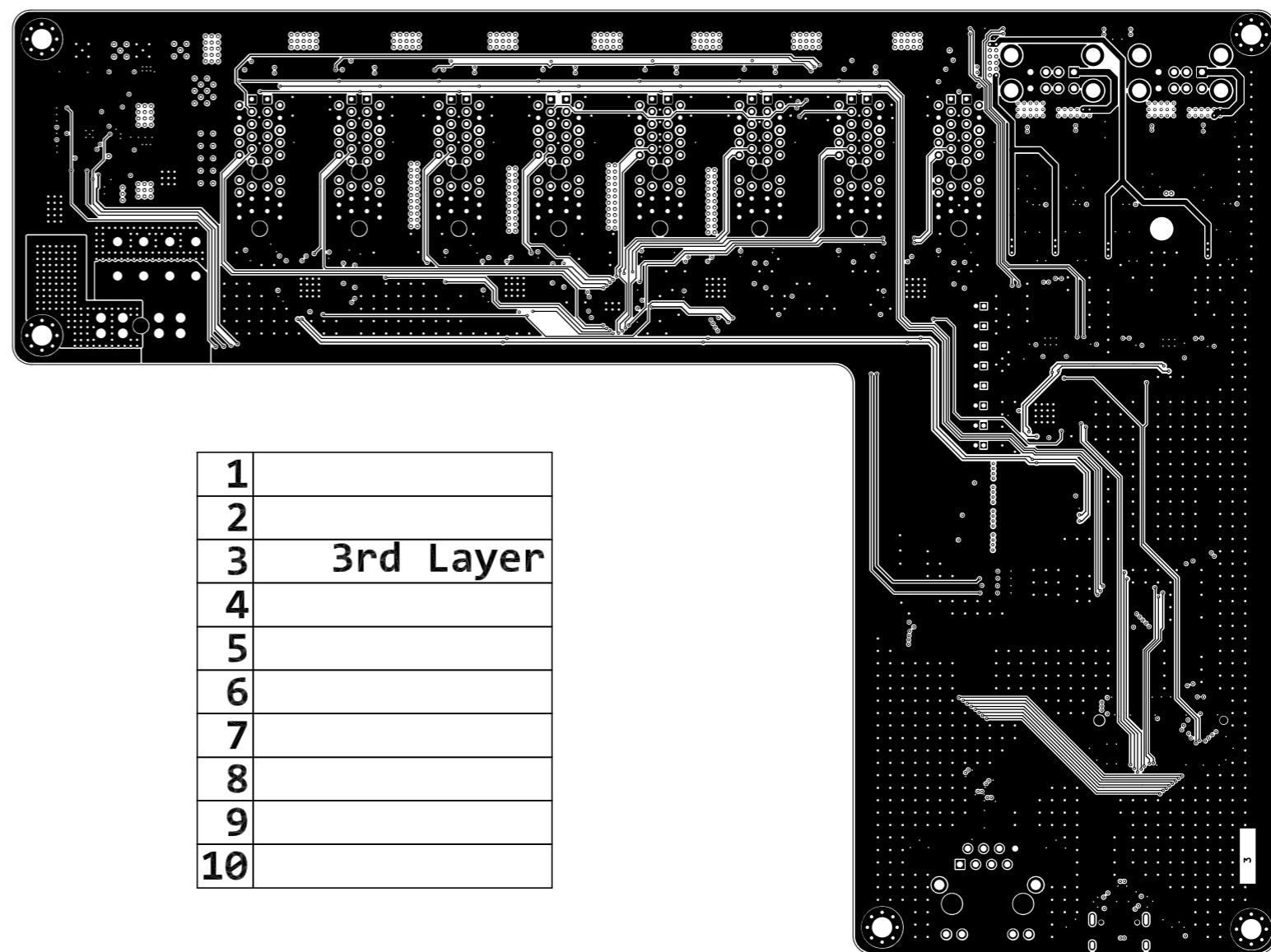
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)



| | |
|---|---|
| Board Name: PDNode-600 | Project Name: Baseboard |
| Date: PDNode_Baseboard.kicad_pcb | Revision: Variant: Pro |
| Sheet Title: Company: Designer: David Sipos Reviewer: | Size: A3 Sheet: 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

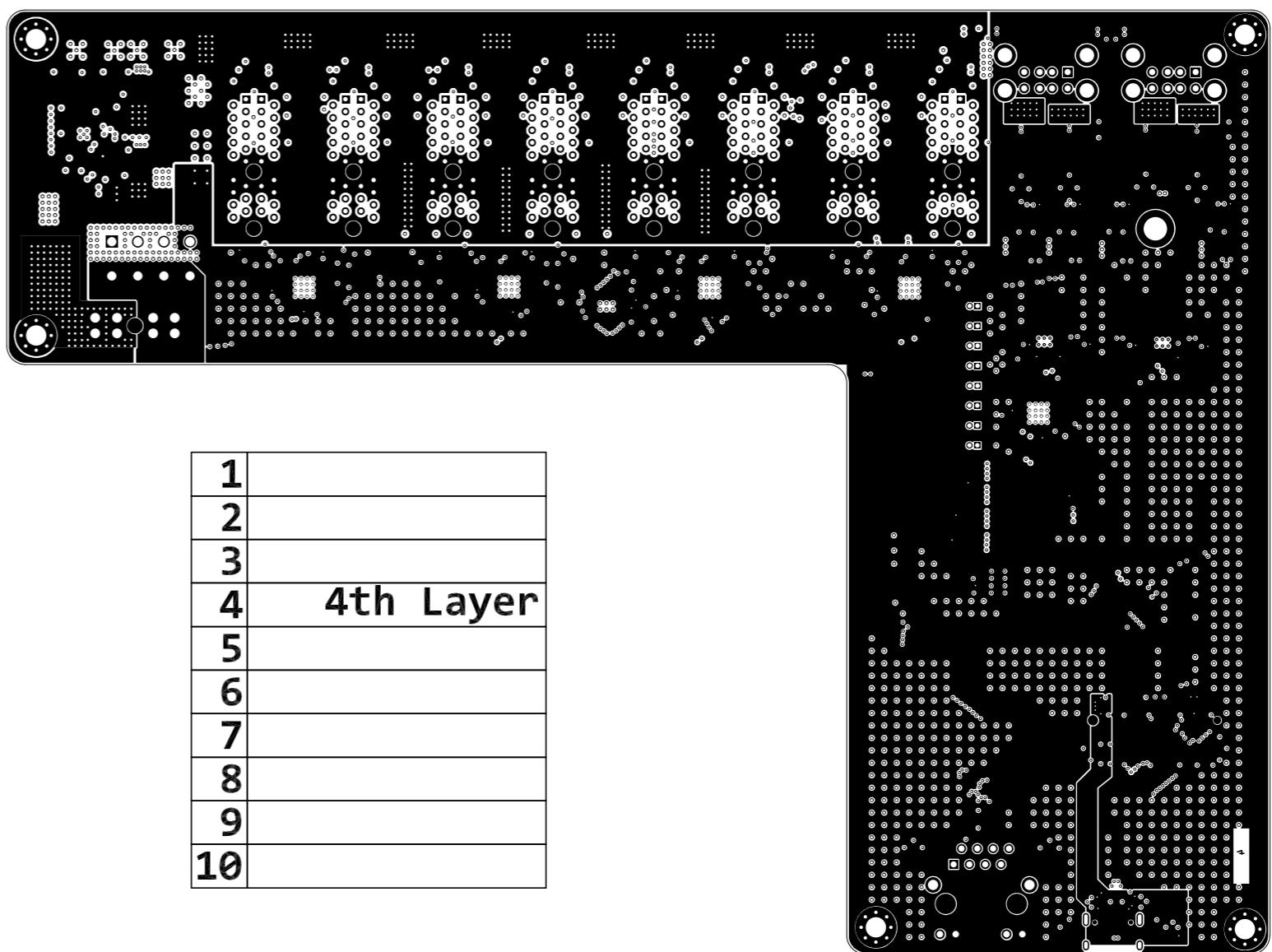
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- △ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | | |
|-------|----------------------------|---------------|---------------------------------------|
| | Board Name: | Project Name: | |
| | PDNode-600 | Baseboard | |
| | File Name: | Revision: | |
| | PDNode_Baseboard.kicad_pcb | Variant: | |
| Date: | Sheet Title: | Company: | Designer: David Sipos Reviewer: |
| | | | Size: A3 |
| | | | Sheet: 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

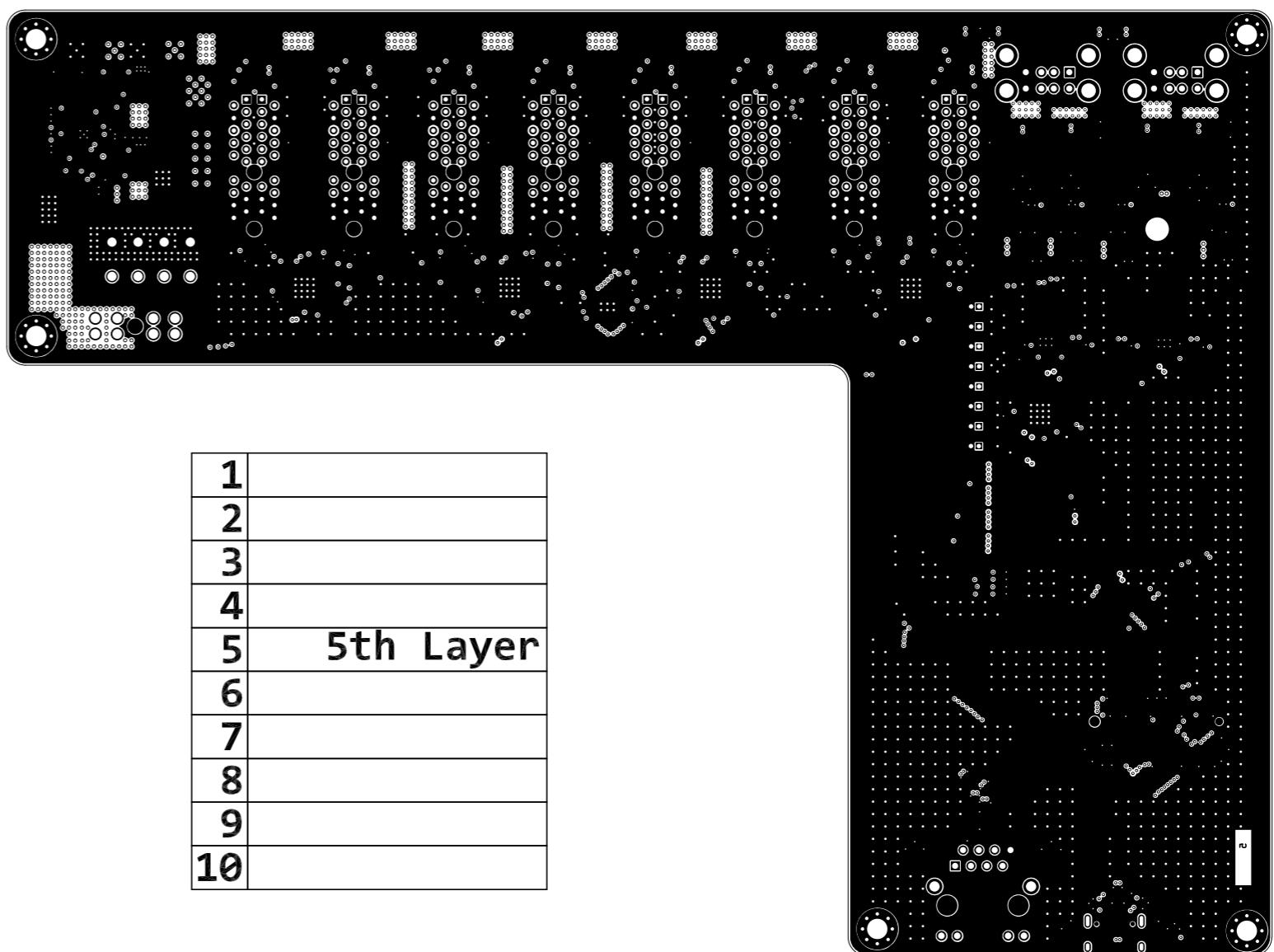
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- △ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | | |
|-------|----------------------------|---------------|---------------------------------------|
| | Board Name: | Project Name: | |
| | PDNode-600 | Baseboard | |
| | File Name: | Revision: | |
| | PDNode_Baseboard.kicad_pcb | Variant: | |
| Date: | Sheet Title: | Company: | Designer: David Sipos Reviewer: |
| | | | Size: A3 |
| | | | Sheet: 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

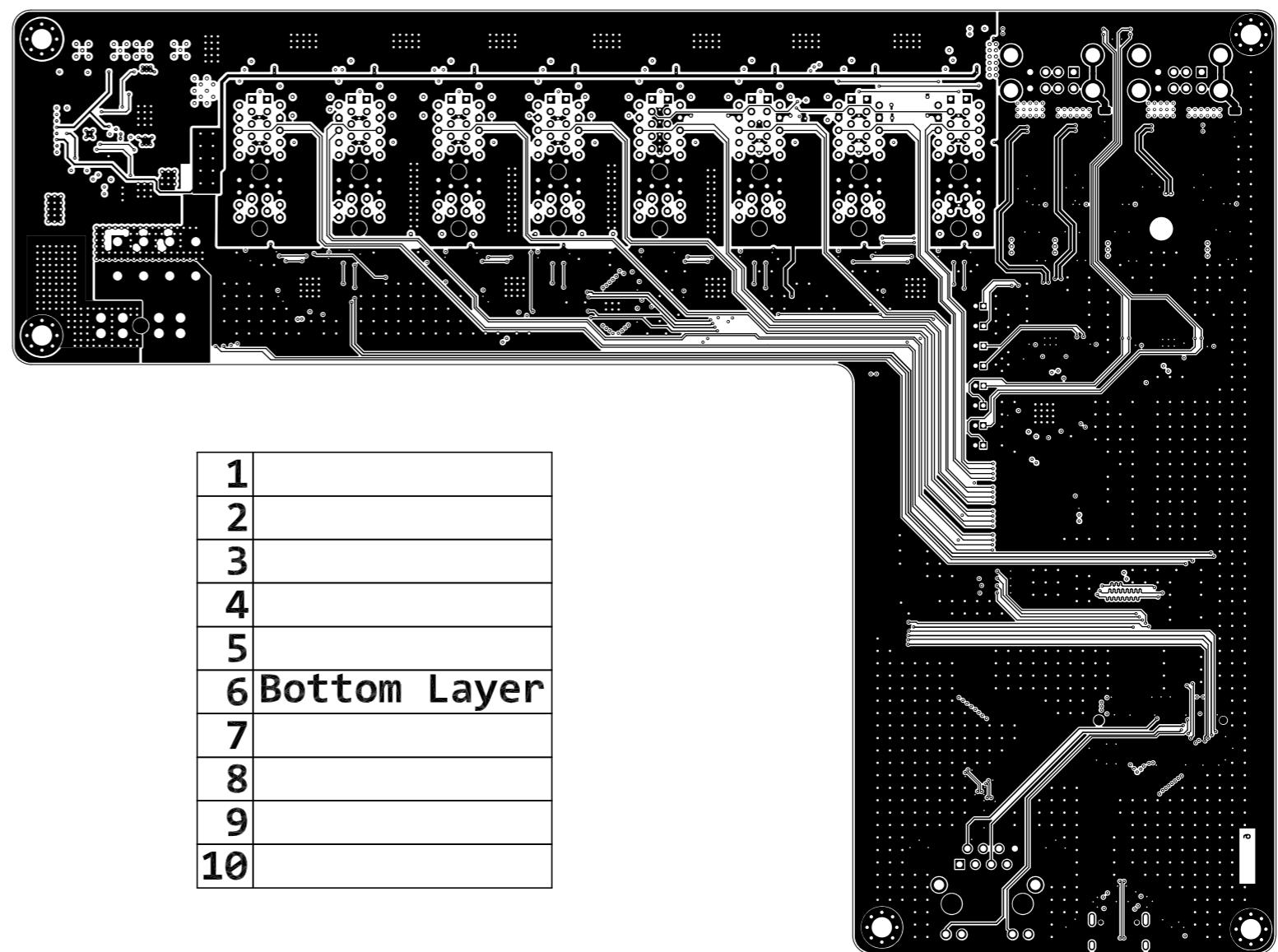
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- △ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | | |
|-------|----------------------------|------------------------------------|--------------|
| | Board Name: | Project Name: | |
| | PDNode-600 | Baseboard | |
| | File Name: | Revision: | |
| | PDNode_Baseboard.kicad_pcb | Variant: | |
| Date: | Sheet Title: | Company: | Size: Sheet: |
| | | Designer: David Sipos Reviewer: | A3 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

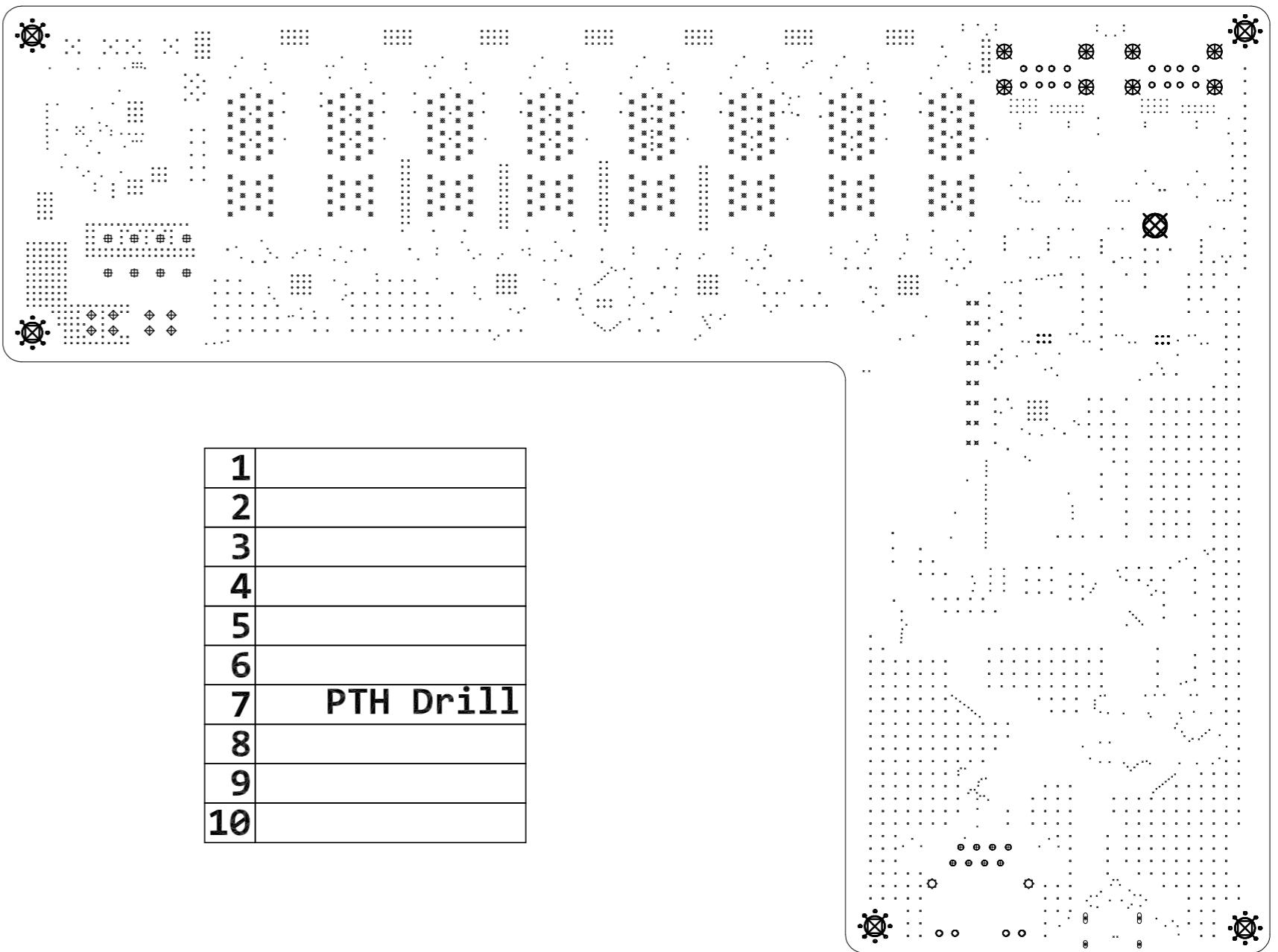
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- △ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | |
|--------------|--|------------------------------------|
| | Board Name: PDNode-600 | Project Name: Baseboard |
| Date: | File Name: PDNode_Baseboard.kicad_pcb | Revision: Variant: Pro |
| Sheet Title: | Company: | Designer: David Sipos Reviewer: |
| Size: A3 | Sheet: 1 of 1 | |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

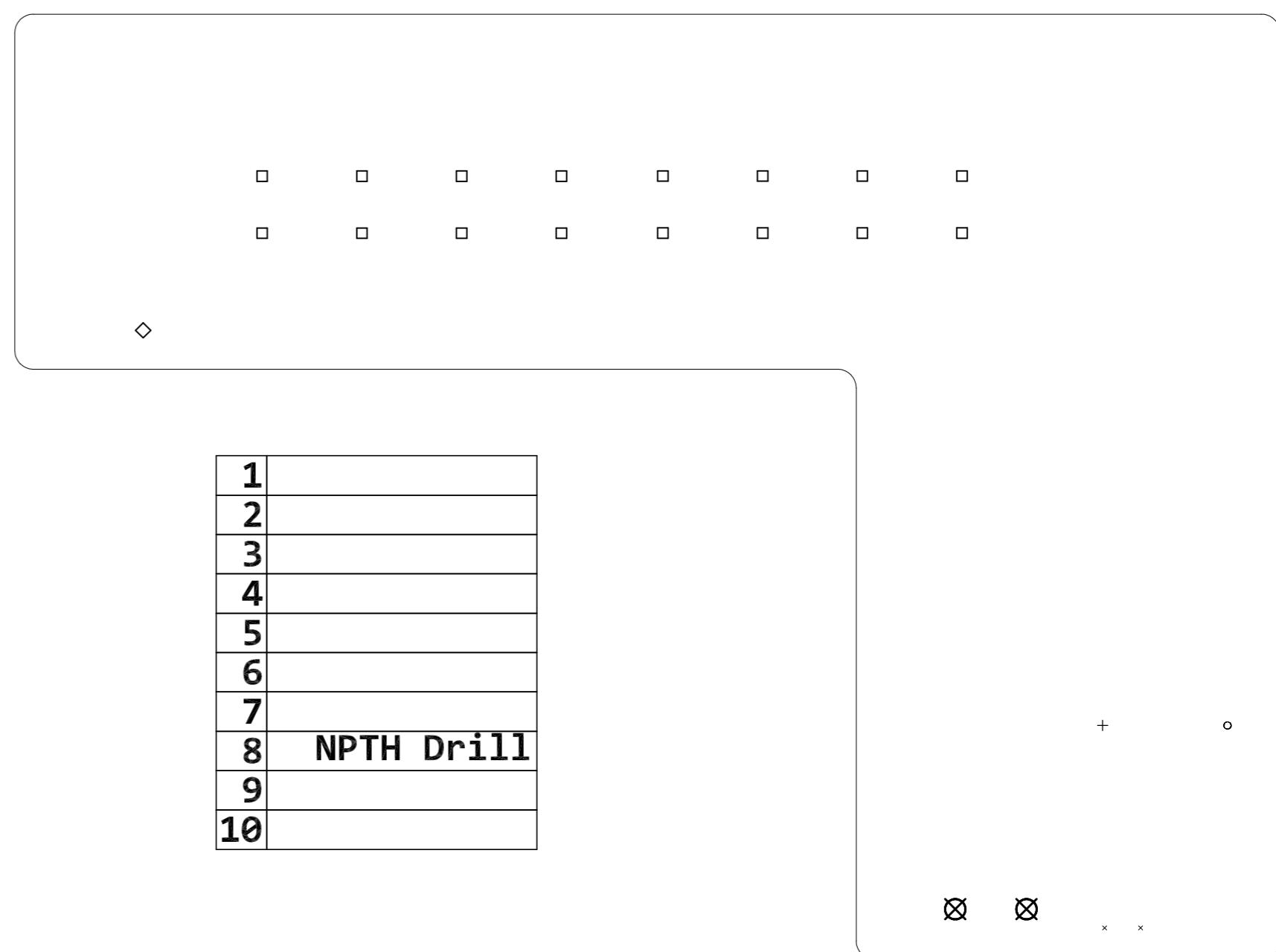
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ☒ 3.250mm / 0.1280" (2 holes) (not plated)



| | |
|---|---------------------------------|
| Board Name: PDNode-600 | Project Name: Baseboard |
| Date: PDNode_Baseboard.kicad_pcb | Revision: Variant: Pro |
| Sheet Title: Company: Designer: David Sipos Reviewer: | Size: A3 Sheet: 1 of 1 |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 u"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

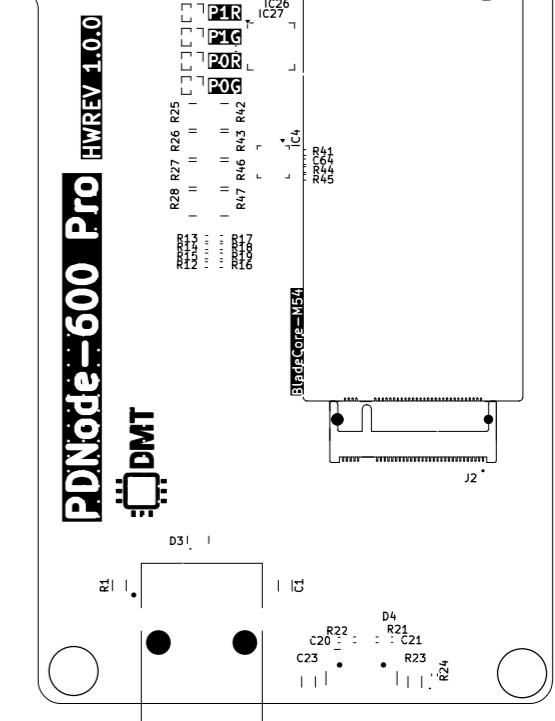
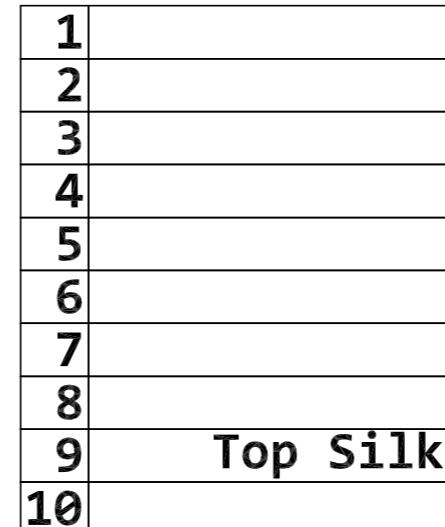
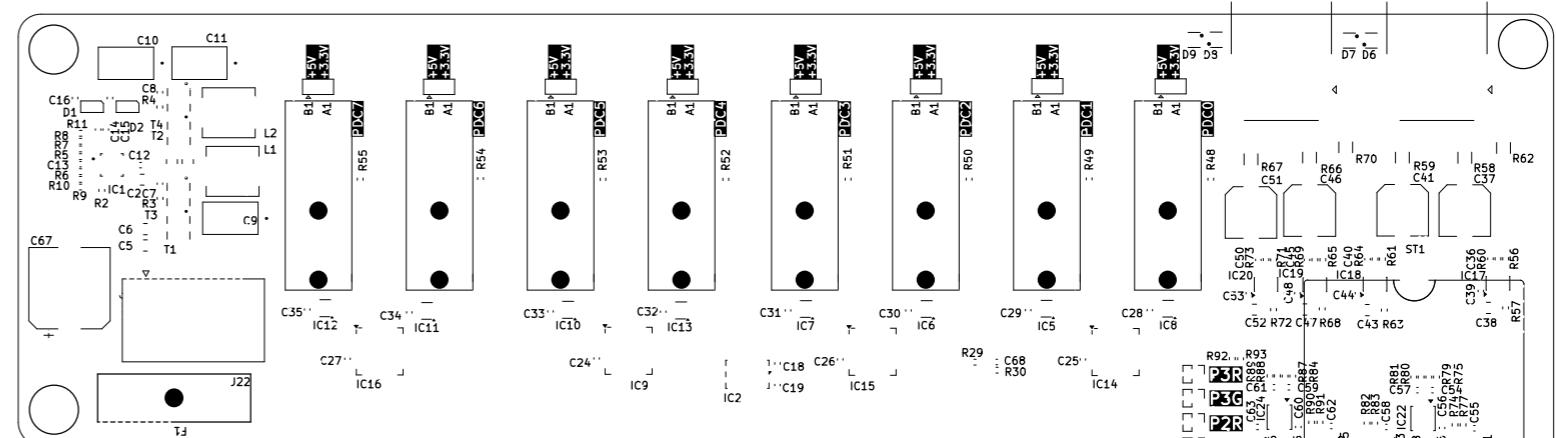
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- * 0.600mm / 0.0236" (0 holes + 4 slots)
- * 0.650mm / 0.0256" (16 holes)
- * 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- ◊ 1.400mm / 0.0551" (8 holes)
- ◊ 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- ⊗ 2.300mm / 0.0906" (8 holes)
- ⊗ 3.200mm / 0.1260" (5 holes)
- ⊗ 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | | |
|--------------|----------------------------|---------------|--------|
| | Board Name: | Project Name: | |
| | PDNode-600 | Baseboard | |
| | File Name: | Revision: | |
| | PDNode_Baseboard.kicad_pcb | Variant: | |
| Date: | Pro | | |
| Sheet Title: | Company: | | Size: |
| | Designer: David Sipos | | A3 |
| | Reviewer: | | Sheet: |
| | 1 of 1 | | |

Baseboard Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 203.00 mm x 151.75 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: No

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

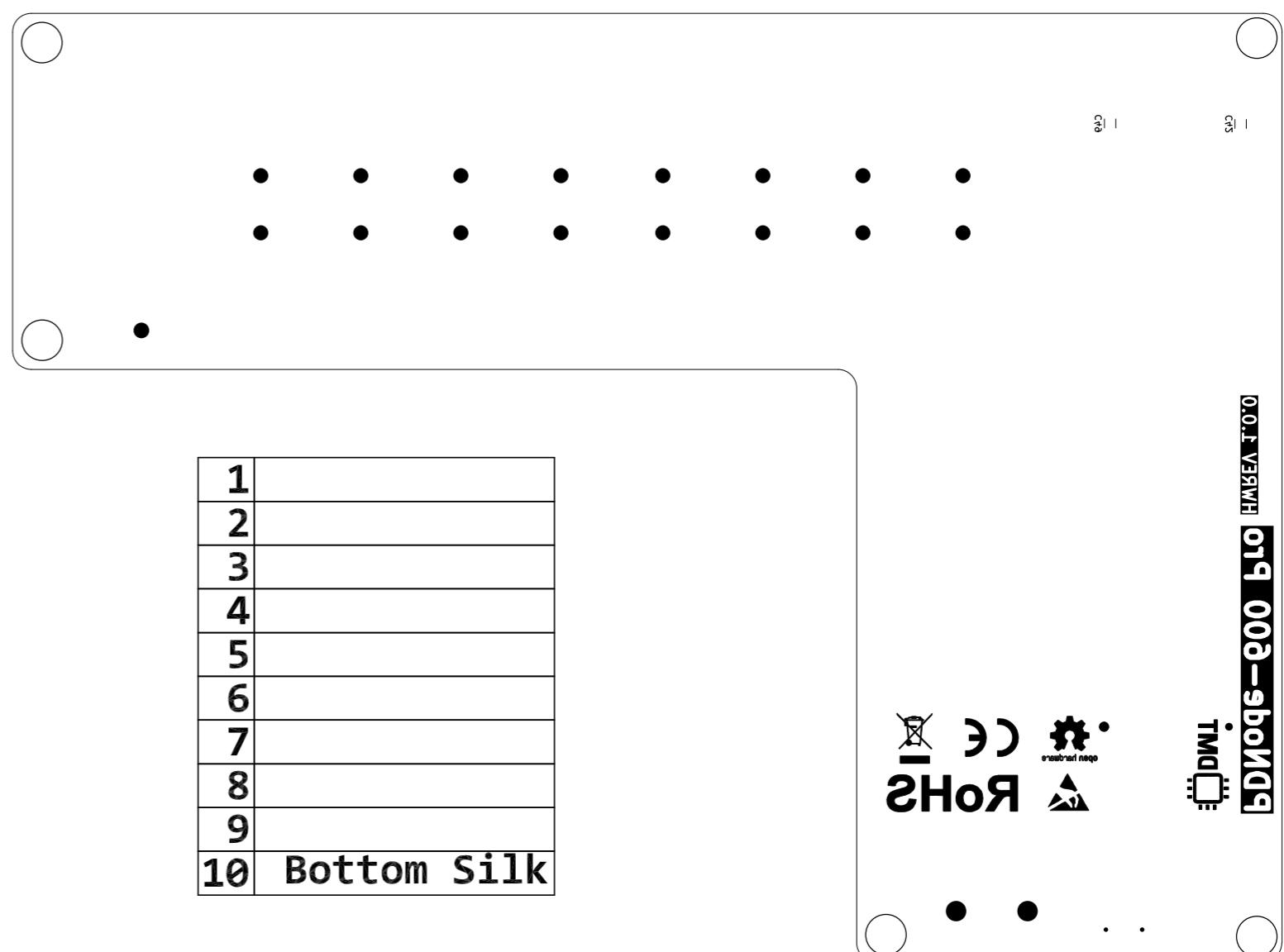
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

Electrical Test: Flying Probe Fully Test

LAYER STACKUP

| Name | Type | Material | Thickness mm | Er | LossTg |
|--------------|-------------|---------------------------|--------------|------|--------|
| F.Silkscreen | Top Silk | Direct Printing White | - | - | - |
| F.Paste | Paste | - | - | - | - |
| F.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| F.Cu | Copper | - | 0.035 | - | - |
| Dielectric 1 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| In1.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 2 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In2.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 3 | Prepreg | 2116 RC54% 4.9mil | 0.1088 | 4.16 | 0.02 |
| In3.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 4 | Core | 0.55mm H/H without copper | 0.55 | 4.41 | 0.02 |
| In4.Cu | Copper | - | 0.0152 | - | - |
| Dielectric 5 | Prepreg | 3313 RC57% 4.2mil | 0.0994 | 4.1 | 0.02 |
| B.Cu | Copper | - | 0.035 | - | - |
| B.Mask | Solder Mask | Solder Resist Green | 0.01 | 3.8 | 0 |
| B.Paste | Paste | - | - | - | - |
| B.Silkscreen | Bottom Silk | Direct Printing White | - | - | - |



PTH DRILLMAP

Drill Map:

- 0.200mm / 0.0079" (552 holes)
- 0.200mm / 0.0079" (12 holes)
- 0.250mm / 0.0098" (54 holes)
- 0.300mm / 0.0118" (1358 holes)
- 0.300mm / 0.0118" (86 holes)
- 0.500mm / 0.0197" (40 holes)
- 0.600mm / 0.0236" (0 holes + 4 slots)
- 0.650mm / 0.0256" (16 holes)
- 0.700mm / 0.0276" (288 holes)
- 0.890mm / 0.0350" (8 holes)
- 0.920mm / 0.0362" (16 holes)
- 1.020mm / 0.0402" (4 holes)
- 1.400mm / 0.0551" (8 holes)
- 1.499mm / 0.0590" (8 holes)
- 1.630mm / 0.0642" (2 holes)
- 2.300mm / 0.0906" (8 holes)
- 3.200mm / 0.1260" (5 holes)
- 3.700mm / 0.1457" (1 hole)

NPTH DRILLMAP

Drill Map:

- × 0.650mm / 0.0256" (2 holes) (not plated)
- 1.150mm / 0.0453" (1 hole) (not plated)
- + 1.650mm / 0.0650" (1 hole) (not plated)
- 2.350mm / 0.0925" (16 holes) (not plated)
- ◊ 2.438mm / 0.0960" (1 hole) (not plated)
- ⊗ 3.250mm / 0.1280" (2 holes) (not plated)

| | | |
|--------------|---------------------------------------|-----------------|
| | Board Name: | Project Name: |
| | PDNode-600 | Baseboard |
| | File Name: | Revision: |
| | PDNode_Baseboard.kicad_pcb | Variant: Pro |
| Sheet Title: | Company: | Size: |
| | Designer: David Sipos Reviewer: | A3 |
| Sheet: | 1 of 1 | |